Call for Papers

2018 Conference of the IEEE Technology&Engineering Management Society

TEMSCON 2018

Orrington Hotel
Evanston, IL USA
June 28-June 30, 2018

Engineering Management in an era of disruption

We invite contributions from researchers, educators, managers and students. Contributions may be conceptual, theoretical, or empirical. They should document research activities, case studies or best practices, shedding light on the theory or practice of engineering, technology, or innovation management, and addressing the strategic objectives of technological change.

There will be an opportunity to publish in ***IEEE Engineering Management Review*** as well as a **Special Issue** of our journal ***IEEE Transactions on Engineering Management*** for selected papers submitted to the conference.

Major topic areas include:

- ***Entrepreneurship and its ecosystem***
- ***Management of innovation***
- ***Technology and engineering management***
- ***Strategy and global markets***
- ***New manufacturing and supply chain systems***
- ***Biotech and Healthcare Innovation,***
- ***Information Technology and the Internet***
- ***Social issues, sustainability, energy and infrastructure***
- ***Executive leadership, people and organizations***
- ***Special topic area: Impact of disruptive technologies on management***

In addition to these core topics, we have special sessions on management during these challenging times as seen by IEEE societies. For topic details, see us at www.temscon.org. We will also be hosting:

Education programs in Technology and Engineering Management
Speakers and panels on disruptive technologies and business and managerial practices
Tours of Chicago area technology and innovation centers
Editor's Panel – publication outlets in Technology and Engineering Management

This event will include an Industry Forum on Technology Management Challenges in today's world- June 29, 2018

Important Dates:

- Paper Submission Due: **1 February 2018**
- Early Bird Registration Begins **15 January 2018**
- Notification of Acceptance: **1 March 2018**
- Author Registration Due: **15 April 2018**
- Regular Registration: **15 March thru 20 June 2018**
- Hotel Block Deadline: **7 June 2018**

Organizing Committee:

General Co-Chairs*: Mark Werwath, TEMS VP of Publications, Bakul Banerjee, Chair of TEMS Chicago Chapter*
Program Co-Chairs*: Peggy Matson, Northwestern University, Jason Hui, BAE Systems, Tugrul Daim, Portland State*
For additional information, visit the conference web page at www.temscon.org